

N-Channel Enhancement Mode MOSFET

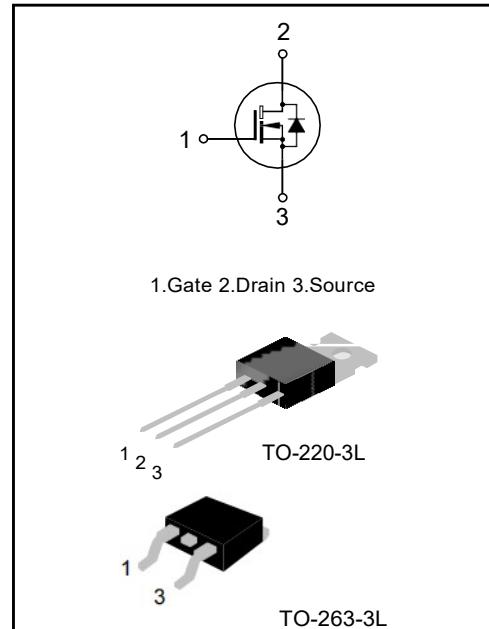
Product Information

Features

- ◆ Surface-mounted package
- ◆ Super Trench
- ◆ Advanced trench cell design Applications
- ◆ LCD TV appliances
- ◆ LCDM appliances
- ◆ High power inverter system

Quick reference

- ◆ **BV ≥ 150 V Ptot ≤ 156 W ID ≤ 120 A**
- ◆ **RDS(ON) $\leq 8.8\text{m}\Omega$ @ VGS = 10 V**
- ◆ **RDS(ON) $\leq 9.8\text{m}\Omega$ @ VGS = 6 V**



Package Marking and Ordering Information:



Marking	Part #	Package	Packing	Qty.
SR080N15T	SR080N15T	TO-220	Tube	50 units
SR080N15S	SR080N15S	TO-263	Tube	50 units

Limiting Values

Symbol	Parameter	Conditions	Min	Max	Unit
V _{DS}	Drain-Source Voltage	T _C = 25 °C	150	-	V
V _{GS}	Gate-Source Voltage	T _C = 25 °C	-	± 25	V
I _D *	Drain Current (DC)	T _C = 25 °C, V _{GS} = 10 V	-	120	A
		T _C = 100 °C, V _{GS} = 10 V	-	86	A
I _{DM} ***	Drain Current (Pulsed)	T _C = 25 °C, V _{GS} = 10 V	-	240	A
P _{tot} *	Drain power dissipation	T _C = 25 °C	-	156	W
T _{stg}	Storage Temperature		-55	150	°C
T _J	Junction Temperature		-	150	°C
I _S	Continuous-Source Current	T _C = 25 °C	-	120	A
E _{AS} *	Single Pulsed Avalanche Energy	V _{DD} = 50 V, L = 1 mH	-	684	mJ
R _{θJA} *	Thermal Resistance- Junction to Ambient		-	62.5	°C/W
R _{θJC} *	Thermal Resistance- Junction to Case		-	0.8	

Notes :

* Surface Mounted on 1 in² pad area, t ≤ 10 sec

** Pulse width ≤ 300 μ s, duty cycle ≤ 2 %

*** Limited by bonding wire

Electrical Characteristics

(TA=25 ° Unless Otherwise Noted)

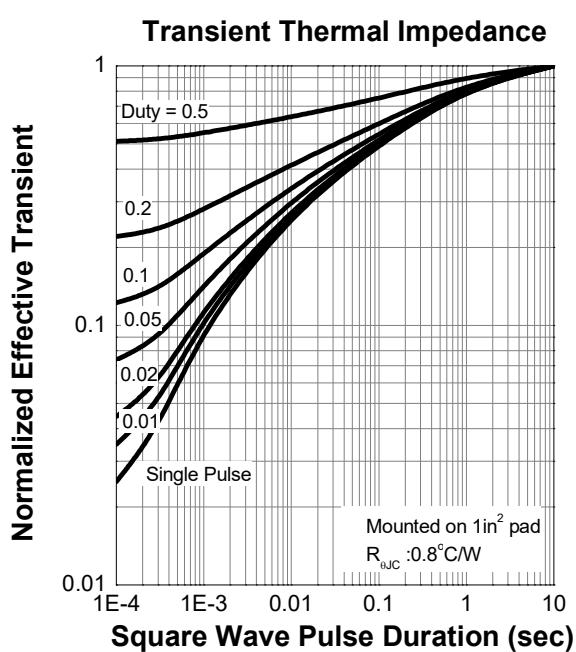
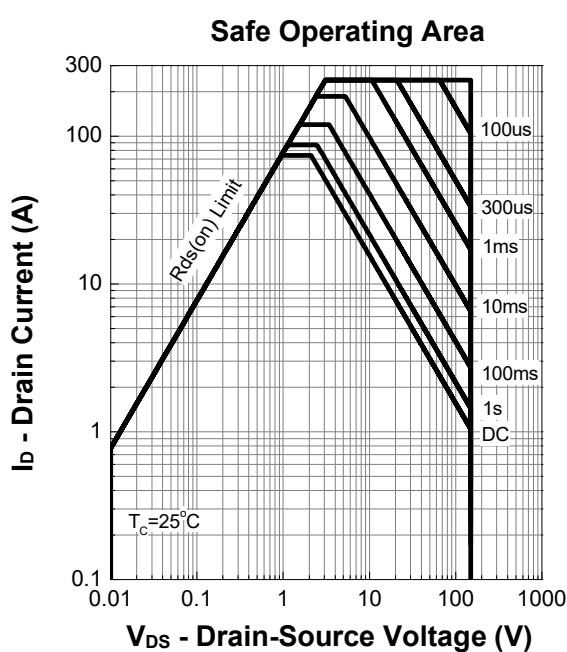
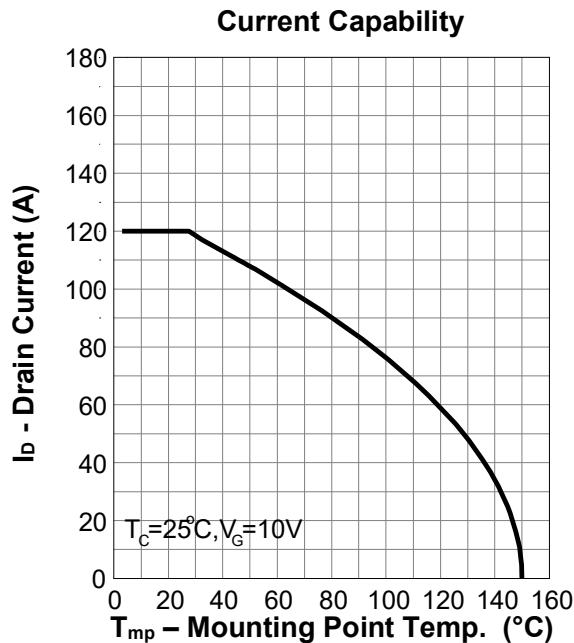
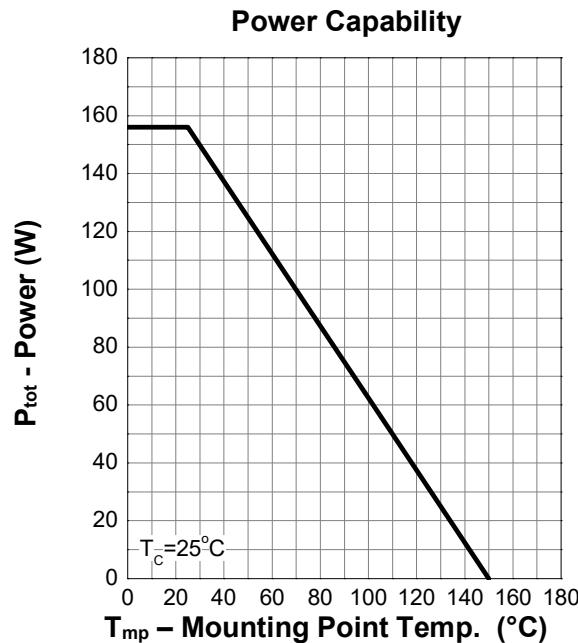
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _{DS} = 250 μA	150	-	-	V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _{DS} = 250 μA	2	-	4	V
I _{DSS}	Drain Leakage Current	V _{DS} = 120 V, V _{GS} = 0 V	-	-	1	μA
I _{GSS}	Gate Leakage Current	V _{GS} = 0 V, V _{GS} = ± 25 V	-	-	±100	nA
R _{Ds(on)^a}	On-State Resistance	V _{GS} = 10 V, I _{DS} = 30 A	-	8.3	8.8	mΩ
		V _{GS} = 6 V, I _{DS} = 20 A	-	9.3	9.8	
Diode Characteristics						
V _{SD^a}	Diode Forward Voltage	I _{SD} = 30 A, V _{GS} = 0 V	-	-	1.3	V
t _{rr}	Reverse Recovery Time	I _{DS} = 30 A, dI _{SD} /dt = 100 A/μs	-	96	-	nS
Q _{rr}	Reverse Recovery Charge		-	355	-	nC
Dynamic Characteristics ^b						
C _{iss}	Input Capacitance	V _{GS} = 0 V, V _{DS} = 75 V Frequency = 1 MHz	-	4756	-	pF
C _{oss}	Output Capacitance		-	318	-	
C _{rss}	Reverse Transfer Capacitance		-	65	-	
t _{d(on)}	Turn-on Delay Time	V _{DS} = 75 V, V _{GEN} = 10 V, R _G = 3.9 Ω, R _L = 2.5 Ω, I _{DS} = 30 A	-	19	-	nS
t _r	Turn-on Rise Time		-	69	-	
t _{d(off)}	Turn-off Delay Time		-	55	-	
t _f	Turn-off Fall Time		-	80	-	
Gate Charge Characteristics ^b						
Q _g	Total Gate Charge	V _{DS} = 75 V, V _{GS} = 10 V, I _{DS} = 30 A	-	81	-	nC
Q _{gs}	Gate-Source Charge		-	27	-	
Q _{gd}	Gate-Drain Charge		-	17	-	

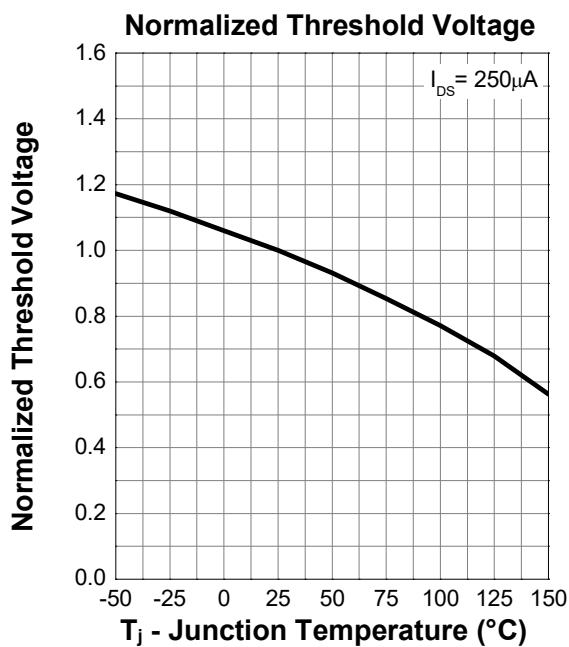
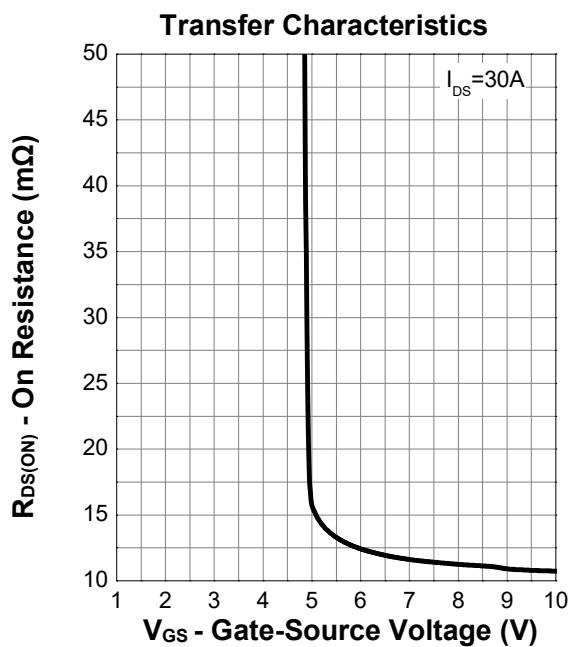
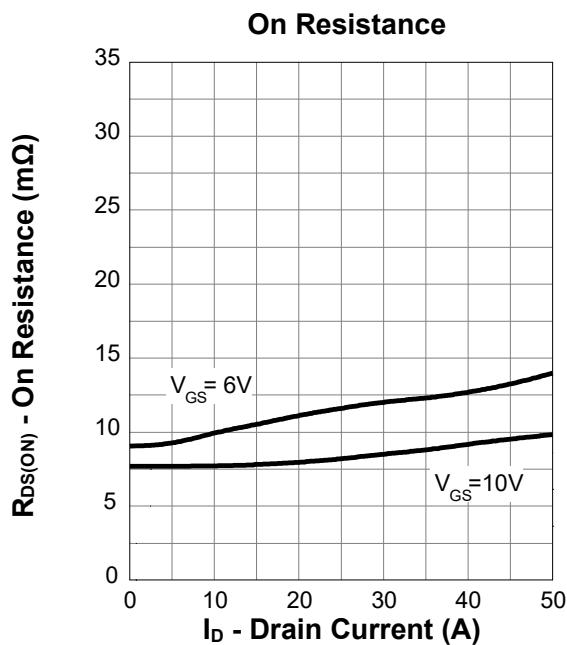
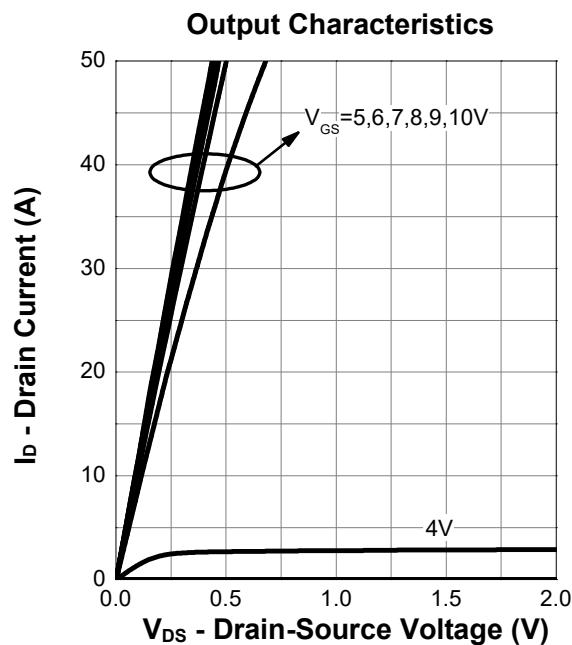
Notes :

a : Pulse test ; pulse width ≤ 300 μs, duty cycle ≤ 2%

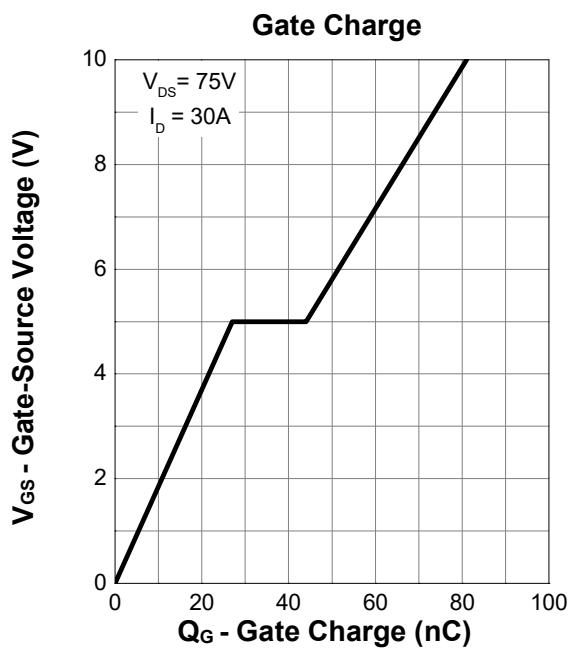
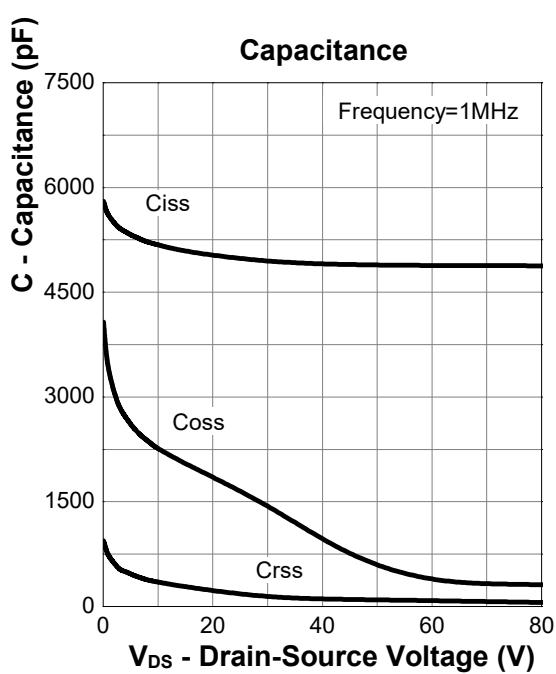
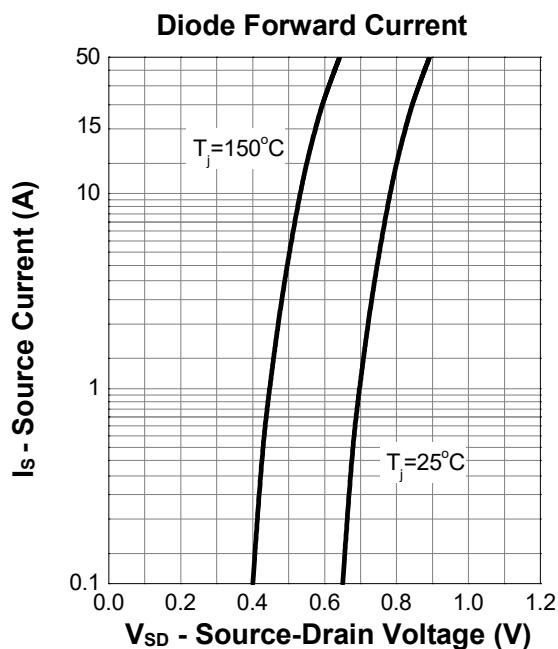
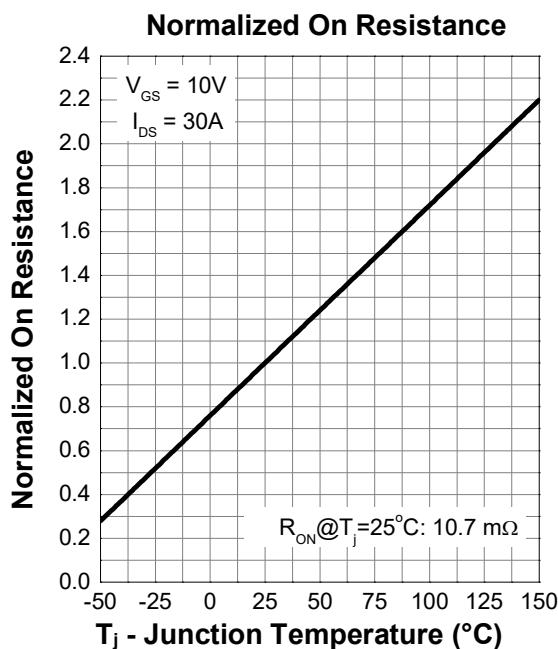
b : Guaranteed by design, not subject to production testing

Typical Characteristics



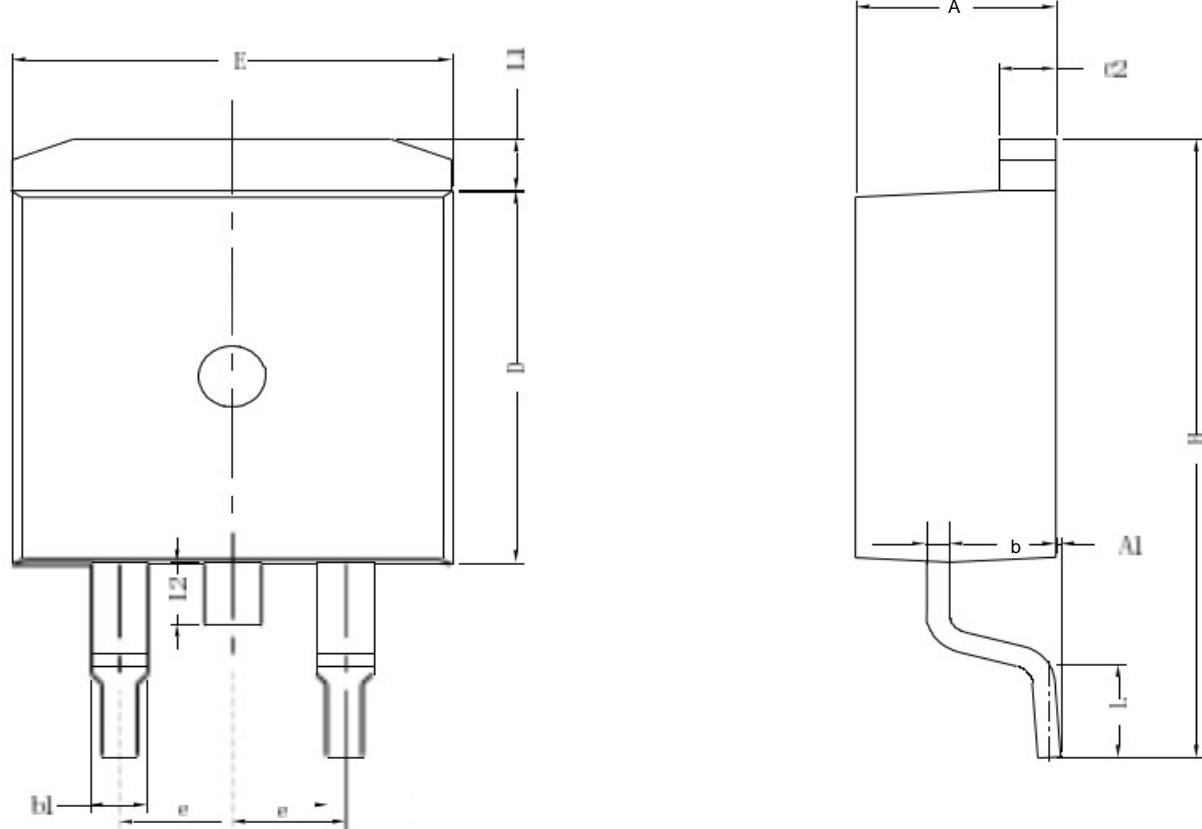
Typical Characteristics (cont.)


Typical Characteristics (cont.)



Package Dimensions

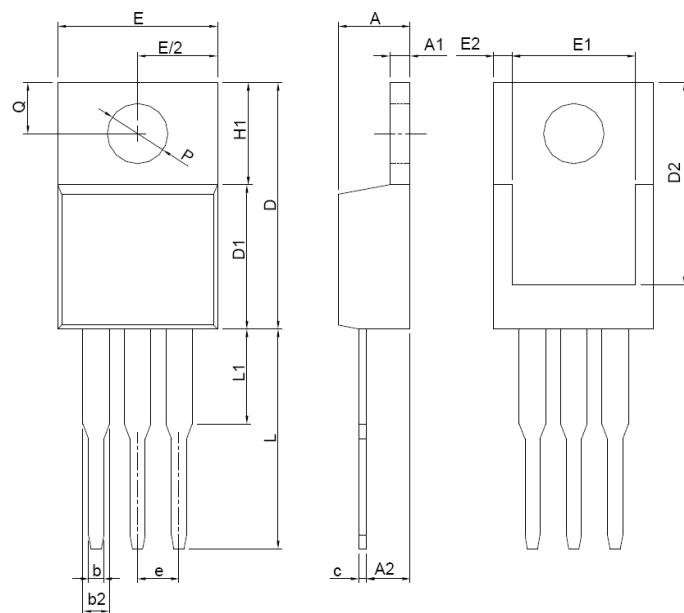
TO-263-3L



Symbol	Dimensions In Millimeters	
	MIN.	MAX.
A	4.3	4.72
A1	0	1.0
b	0.71	0.91
b2	0.30	0.60
C	1.17	1.37
D	8.5	9.35
E	9.8	10.45
E1	6.86	8.89
e	2.54BSC	
H1	14.7	15.75
L	2	2.74
L1	1.12	1.42
L2		1.75

Package Dimensions

TO-220-3L



Symbol	Dimensions In Millimeters	
	MIN.	MAX.
A	3.56	4.83
A1	0.51	1.40
A2	2.03	2.92
b	0.38	1.02
b2	1.14	1.78
c	0.36	0.61
D	14.22	16.51
D1	8.38	9.02
D2	12.19	12.88
E	9.65	10.67
E1	6.86	8.89
E2	0.76BSC	
e	2.54BSC	
H1	5.84	6.86
L	12.70	14.73
L1	6.35BSC	
P	3.53	4.09
Q	2.54	3.43